

BASIS FOR THE AMENDMENT

Claims 4, 12, 17, 22, 27, 33, 39, 43, 47, and 51 have been amended.

The amendment of Claims 4, 12, 17, 22, 27, 33, 39, 43, 47, and 51 is supported by the Examples (page 29, line 21 to page 40, line 2) and by Claims 5, 13, 18, 23, 28, 34, 40, 44, 48, and 52, respectively. The amendment of Claims 4, 12, 17, 22, 27, 33, 39, 43, 47, and 51 serves to provide proper antecedent basis for the compounds listed in Claims 5, 13, 18, 23, 28, 34, 40, 44, 48, and 52, respectively.

No new matter is believed to have been entered by the present amendment.

REMARKS

Claims 1-54 are pending in the present application.

Applicants affirm the election, with traverse, of "A heterocyclic compound with a heteropentacycle, with no benzene ring forming the skeleton, and with a functional group," for further prosecution. If further election is required, Applicants affirm the election, with traverse, of 7-hydroxy-5-alkyl-1,3,4-triazaindolizine, for further prosecution. In view of the amendment to the Claims provided herein, Claims 1-54 now read on the elected species.

For the reasons presented in the Preliminary Amendment and Response to Election of Species Requirement filed on August 19, 2002, Applicants submit that the Office has failed to meet the burden necessary in order to sustain the Election of Species Requirement. Withdrawal of the Election of Species Requirement is respectfully requested.

Applicants submit that this application is now in condition for examination on the merits and an early notification to that effect is earnestly solicited.

Respectfully submitted,

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IN THE CLAIMS

Please amend the claims as follows:

4. (Amended) An aqueous dispersion for chemical mechanical polishing defined in Claim 3, wherein said organic compound is at least one from among (1) biphenol, (2) bipyridyl, (3) vinylpyridine, (4) hypoxanthine, (5) guanine, (6) salicylaldoxime, (7) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to an alkylene group, (8) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to a benzene ring, (9) a heterocyclic compound with a heteropentacycle and with no benzene ring forming the skeleton and with a functional group, (10) a heterocyclic compound with a heteropentacycle and with a benzene ring forming the skeleton, (11) a heterocyclic compound with a heterohexacycle bearing two or more hetero atoms and with either or both a functional group and/or a benzene ring forming the skeleton, and a derivative of any of compounds (1) through (11).

12. (Amended) An aqueous dispersion for chemical mechanical polishing defined in any one of Claim 11, wherein said organic compound is at least one from among (1) biphenol, (2) bipyridyl, (3) vinylpyridine, (4) hypoxanthine, (5) adenine, (6) guanine, (7) salicylaldoxime, (8) copperon, (9) cysteine, (10) thiourea, (11) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to an alkylene group, (12) a

compound with a total of two or more amino groups and/or hydroxyl groups bonded to a benzene ring, (13) a heterocyclic compound with a heteropentacycle and with no benzene ring forming the skeleton and with a functional group, (14) a heterocyclic compound with a heteropentacycle and with a benzene ring forming the skeleton, (15) a heterohexacyclic compound bearing two or more hetero atoms, and a derivative of any of compounds (1) through (15).

17. (Amended) An aqueous dispersion for chemical mechanical polishing defined in Claim 16, wherein said organic compound is at least one from among (1) biphenol, (2) bipyridyl, (3) vinylpyridine, (4) hypoxanthine, (5) adenine, (6) guanine, (7) salicylaldehyde, (8) copperon, (9) cysteine, (10) thiourea, (11) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to an alkylene group, (12) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to a benzene ring, (13) a heterocyclic compound with a heteropentacycle and with no benzene ring forming the skeleton and with a functional group, (14) a heterocyclic compound with a heteropentacycle and with a benzene ring forming the skeleton, (15) a heterohexacyclic compound bearing two or more hetero atoms, and a derivative of any of compounds (1) through (15).

22. (Amended) An aqueous dispersion for chemical mechanical polishing defined in Claim 21, wherein said organic compound is at least one from among (1) biphenol, (2) bipyridyl, (3) vinylpyridine, (4) hypoxanthine, (5) adenine, (6) guanine, (7) salicylaldehyde, (8) copperon, (9) cysteine, (10) thiourea, (11) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to an alkylene group, (12) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to a benzene ring, (13) a heterocyclic compound with a heteropentacycle and with no benzene ring forming the

skeleton and with a functional group, (14) a heterocyclic compound with a heteropentacycle and with a benzene ring forming the skeleton, (15) a heterohexacyclic compound bearing two or more hetero atoms, and a derivative of any of compounds (1) through (15).

27. (Amended) An aqueous dispersion for chemical mechanical polishing defined in Claim 26, wherein said organic compound is at least one from among (1) biphenol, (2) bipyridyl, (3) vinylpyridine, (4) hypoxanthine, (5) adenine, (6) guanine, (7) salicylaldoxime, (8) copperon, (9) cysteine, (10) thiourea, (11) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to an alkylene group, (12) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to a benzene ring, (13) a heterocyclic compound with a heteropentacycle and with no benzene ring forming the skeleton and with a functional group, (14) a heterocyclic compound with a heteropentacycle and with a benzene ring forming the skeleton, (15) a heterohexacyclic compound bearing two or more hetero atoms, and a derivative of any of compounds (1) through (15).

33. (Amended) A method of inhibiting generation of pits on a polishing surface of an object in need thereof, comprising:

mixing an aqueous dispersion comprising water, an abrasive, and one or more organic compounds selected from the group consisting of (1) biphenol, (2) bipyridyl, (3) vinylpyridine, (4) hypoxanthine, (5) guanine, (6) salicylaldoxime, (7) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to an alkylene group, (8) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to a benzene ring, (9) a heterocyclic compound with a heteropentacycle and without a benzene ring forming the skeleton and with a functional group, (10) a heterocyclic compound with a heteropentacycle and with a benzene ring forming the skeleton, (11) a heterocyclic compound

with a heterohexacycle bearing two or more hetero atoms and with either or both a functional group and/or a benzene ring forming the skeleton, and (12) a derivative of any of compounds (1) through (11);

supplying said aqueous dispersion to the surface of a polishing pad; and

chemical mechanical polishing a polishing surface of an object in need thereof in the presence of said aqueous dispersion.

39. (Amended) A method of suppressing reduction of performance of a polishing pad of an object in need thereof and inhibiting generation of pits on a polishing surface of an object in need thereof, comprising:

— — — — mixing an aqueous dispersion comprising water, an abrasive, and one or more organic compounds selected from the group consisting of (1) biphenol, (2) bipyridyl, (3) vinylpyridine, (4) hypoxanthine, (5) adenine, (6) guanine, (7) salicylaldehyde, (8) copperon, (9) cysteine, (10) thiourea, (11) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to an alkylene group, (12) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to a benzene ring, (13) a heterocyclic compound with a heteropentacycle, without a benzene ring forming the skeleton and with a functional group, (14) a heterocyclic compound with a heteropentacycle, with a benzene ring forming the skeleton, (15) a heterohexacyclic compound bearing two or more hetero atoms, and (16) a derivative of any of compounds (1) through (15);

supplying said aqueous dispersion to the surface of a polishing pad; and

chemical mechanical polishing a polishing surface of an object in need thereof in the presence of said aqueous dispersion.

43. (Amended) A method of suppressing reduction of performance of a polishing pad

of an object in need thereof and flattening uneven sections on a polishing surface of an object in need thereof, comprising:

mixing an aqueous dispersion comprising water, an abrasive, and one or more organic compounds selected from the group consisting of (1) biphenol, (2) bipyridyl, (3) vinylpyridine, (4) hypoxanthine, (5) adenine, (6) guanine, (7) salicylaldehyde, (8) copperon, (9) cysteine, (10) thiourea, (11) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to an alkylene group, (12) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to a benzene ring, (13) a heterocyclic compound with a heteropentacycle, without a benzene ring forming the skeleton and with a functional group, (14) a heterocyclic compound with a heteropentacycle, with a benzene ring forming the skeleton, (15) a heterohexacyclic compound bearing two or more hetero atoms, and (16) a derivative of any of compounds (1) through (15);

supplying said aqueous dispersion to the surface of a polishing pad; and

chemical mechanical polishing a polishing surface of an object in need thereof in the presence of said aqueous dispersion.

47. (Amended) A method of inhibiting generation of pits on a polishing surface of an object in need thereof and flattening uneven sections on a polishing surface of an object in need thereof, comprising:

mixing an aqueous dispersion comprising water, an abrasive, and one or more organic compounds selected from the group consisting of (1) biphenol, (2) bipyridyl, (3) vinylpyridine, (4) hypoxanthine, (5) adenine, (6) guanine, (7) salicylaldehyde, (8) copperon, (9) cysteine, (10) thiourea, (11) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to an alkylene group, (12) a compound with a total of two or more

amino groups and/or hydroxyl groups bonded to a benzene ring, (13) a heterocyclic compound with a heteropentacycle, without a benzene ring forming the skeleton and with a functional group, (14) a heterocyclic compound with a heteropentacycle, with a benzene ring forming the skeleton, (15) a heterohexacyclic compound bearing two or more hetero atoms, and (16) a derivative of any of compounds (1) through (15);

supplying said aqueous dispersion to the surface of a polishing pad; and

chemical mechanical polishing a polishing surface of an object in need thereof in the presence of said aqueous dispersion.

51. (Amended) A method of suppressing reduction of performance of a polishing pad of an object in need thereof, inhibiting generation of pits on a polishing surface of an object in need thereof, and flattening uneven sections on a polishing surface of an object in need thereof, comprising:

mixing an aqueous dispersion comprising water, an abrasive, and one or more organic compounds selected from the group consisting of (1) biphenol, (2) bipyridyl, (3) vinylpyridine, (4) hypoxanthine, (5) adenine, (6) guanine, (7) salicylaldoxime, (8) copperon, (9) cysteine, (10) thiourea, (11) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to an alkylene group, (12) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to a benzene ring, (13) a heterocyclic compound with a heteropentacycle, without a benzene ring forming the skeleton and with a functional group, (14) a heterocyclic compound with a heteropentacycle, with a benzene ring forming the skeleton, (15) a heterohexacyclic compound bearing two or more hetero atoms, and (16) a derivative of any of compounds (1) through (15);

supplying said aqueous dispersion to the surface of a polishing pad; and

chemical mechanical polishing a polishing surface of an object in need thereof in the presence of said aqueous dispersion.